



N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)	
	0.049 at $V_{GS} = 4.5 \text{ V}$	6.1 ^a		
20	0.056 at V _{GS} = 2.5 V	5.7	6.0	
	0.065 at V _{GS} = 1.8 V	5.3		

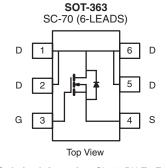
FEATURES

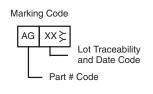
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

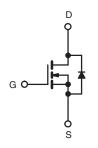


APPLICATIONS

· Load Switch for Portable Devices







Ordering Information: Si1488DH-T1-E3 (Lead (Pb)-free) Si1488DH-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S T _A = 25 °C, unl	ess otherwise	e noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 8	7 v	
	T _C = 25 °C		6.1		
Continuous Dusin Courset /T 150 °C\d	T _C = 70 °C	1 . [4.9		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	l _D	4.6 ^{b, c}		
	T _A = 70 °C	1	3.7 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	20		
Avalanche Current	1 04		10		
Repetitive Avalanche Energy L = 0.1 mH		E _{AS}	5	mJ	
Overhier and Overhead Desire Divide Overhier	T _C = 25 °C		2.3	^	
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	1.3 ^{b, c}	A	
Maximum Power Dissipation ^a	T _C = 25 °C		2.8		
	T _C = 70 °C	1 5 1	1.8	—	
	T _A = 25 °C	P _D	1.5 ^{b, c}	─ W	
	T _A = 70 °C	1	1.0 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	60	80	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	34	45	C/VV	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \quad t=5 \ s.$
- d. Maximum under steady state conditions is 125 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 · · A		20.2		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}$ /	I _D = 250 μA		- 2.75			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.45		0.95	٧	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zana Oaka Walka wa Busin Oanna i	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 85 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 4.6 \text{ A}$		0.041	0.049		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.3 \text{ A}$		0.047	0.056	Ω	
	, ,	V _{GS} = 1.8 V, I _D = 3.9 A		0.054	0.065		
Forward Transconductance	9 _{fs}	V _{DS} = 10 V, I _D = 4.6 A		15		mS	
Dynamic ^b	•		•				
Input Capacitance	C _{iss}			530		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		100			
Reverse Transfer Capacitance	C _{rss}			48			
		$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 4.6 \text{ A}$		6.6 10			
Total Gate Charge	Q_g			6	9	pC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.6 \text{ A}$		1.5			
Gate-Drain Charge	Q _{gd}			0.9			
Gate Resistance	R _q	f = 1 MHz		7.3	11	Ω	
Turn-On Delay Time	t _{d(on)}			8.5	13		
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_1 = 2.7 \Omega$		45	68		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 3.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		35	53	- ns	
Fall Time	t _f			82	123		
Drain-Source Body Diode Characteristic	cs					<u> </u>	
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			2.3		
Pulse Diode Forward Current ^a	I _{SM}				20	A	
Body Diode Voltage	V_{SD}	I _S = 2.2 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10.6	16	nC	
Body Diode Reverse Recovery Charge	Q _{rr}			3.7	5.7		
Reverse Recovery Fall Time	erse Recovery Fall Time t _a			6.2		ns	
Reverse Recovery Rise Time	t _b			4.4		1	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

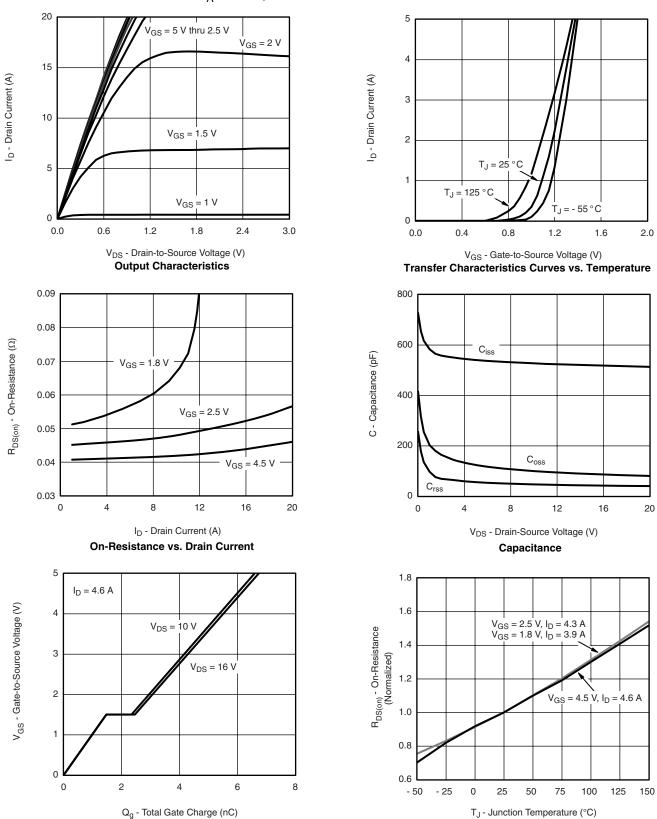
b. Guaranteed by design, not subject to production testing.







TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



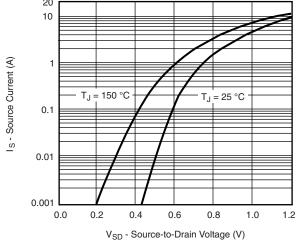
Gate Charge

On-Resistance vs. Junction Temperature

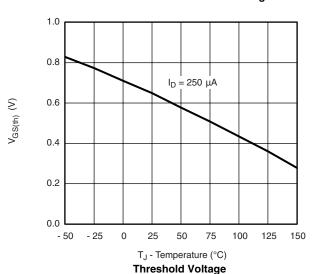
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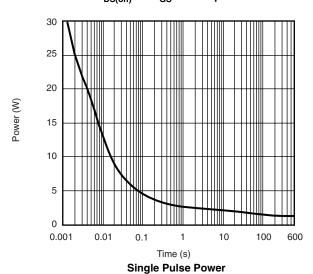


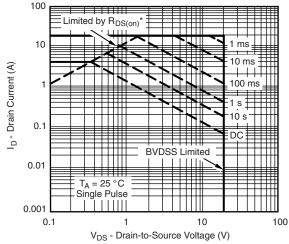
Source-Drain Diode Forward Voltage



0.12 0.09 0.09 0.06 0.06 T_A = 125 °C T_A = 25 °C

 V_{GS} - Gate-to-Source Voltage (V) $\mathbf{R}_{DS(on)}$ vs. V_{GS} vs. Temperature





* $V_{GS} > \mbox{minimum } V_{GS}$ at which $R_{DS(on)}$ is specified

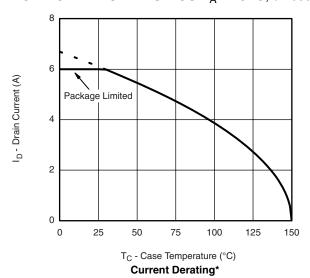
Safe Operating Area, Junction-to-Ambient

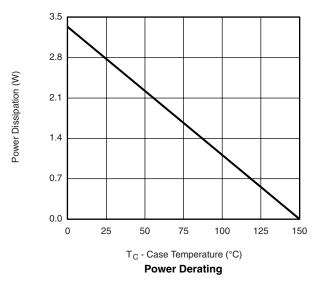






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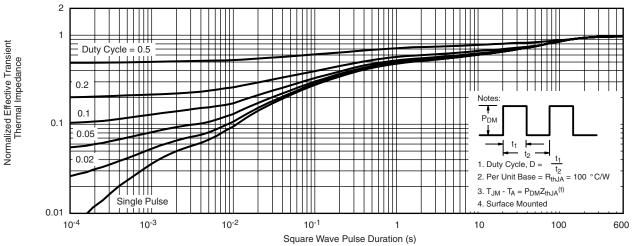


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

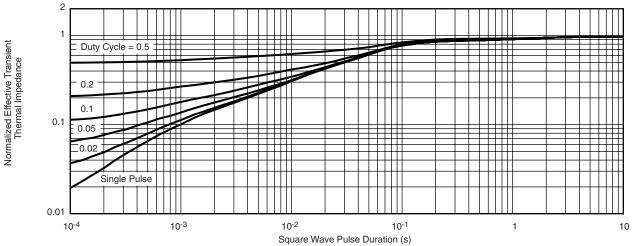
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TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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